

What is claimed is:

1. A semiconductor package comprising:
two substrates each having a chip attach area and a plurality of electrical connection
pads thereon;
5 at least one chip mounted on the chip attach area of each of the substrates and
electrically connected to the electrical connection pads;
two encapsulation bodies respectively formed on the two substrates for encapsulating
the chip on each of the substrates to form two package units; and
a cover for receiving the two package units therein;
10 wherein the substrates and the cover each substantially has a rectangular shape, with a
longer side of each of the substrates being vertical to a longer side of the
cover, and the electrical connection pads of the two substrates are exposed
from the cover and located on the same surface.
2. The semiconductor package as recited in claim 1, wherein the cover is
15 substantially sized 32mm long and 24mm wide.
3. The semiconductor package as recited in claim 1, wherein the substrate is
substantially sized 18mm long and 10 mm wide.
4. The semiconductor package as recited in claim 1, wherein the substrate further
comprises a plurality of passive component attach areas thereon.
- 20 5. The semiconductor package as recited in claim 1, wherein the chip is
electrically connected to the electrical connection pads via a plurality of bonding wires.
6. The semiconductor package as recited in claim 1, wherein the semiconductor
package is a multimedia card (MMC) package.
7. The semiconductor package as recited in claim 1, further comprising another
25 chip stacked on the at least one chip mounted on the substrate.
8. A semiconductor package comprising:
two substrates each having a chip attach area and a plurality of electrical connection
pads thereon;

at least one chip mounted on the chip attach area of each of the substrates and electrically connected to the electrical connection pads;
two encapsulation bodies respectively formed on the two substrates for encapsulating the chip on each of the substrates to form two package units; and
5 a cover for receiving the two package units therein;
wherein the substrates and the cover each substantially has a rectangular shape, with a longer side of each of the substrates being vertical to a longer side of the cover, and the electrical connection pads of the two substrates are exposed from the cover and oppositely arranged.

10 9. The semiconductor package as recited in claim 8, wherein the cover is substantially sized 32mm long and 24mm wide.

10. The semiconductor package as recited in claim 8, wherein the substrate is substantially sized 18mm long and 10 mm wide.

15 11. The semiconductor package as recited in claim 8, wherein the substrate further comprises a plurality of passive component attach areas thereon.

12. The semiconductor package as recited in claim 8, wherein the chip is electrically connected to the electrical connection pads via a plurality of bonding wires.

13. The semiconductor package as recited in claim 8, wherein the semiconductor package is a multimedia card (MMC) package.

20 14. The semiconductor package as recited in claim 8, further comprising another chip stacked on the at least one chip mounted on the substrate.